# Silicon NPN Triple Diffused Character Display Horizontal Deflection Output

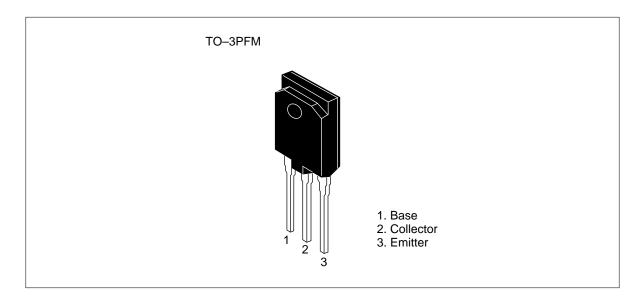
# **HITACHI**

ADE-208-672 (Z) 1st. Edition Oct. 1, 1998

### **Features**

- High breakdown voltage
  - $V_{\text{CBO}} = 1500 \ V$
- High speed switching tf = 0.15 μsec(typ.) at fH=64kHz

#### **Outline**



# **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

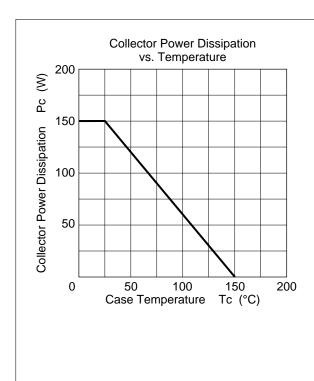
Item	Symbol	Ratings	Unit	
Collector to base voltage	$V_{\text{CBO}}$	1500	V	
Collector to emitter voltage	V <sub>CEO</sub>	700	V	
Emitter to base voltage	$V_{EBO}$	6	V	
Collector current	I <sub>c</sub>	20	Α	
Collector peak current	i <sub>c(peak)</sub>	40	Α	
Collector power dissipation	P <sub>C</sub> <sup>Note1</sup>	150	W	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

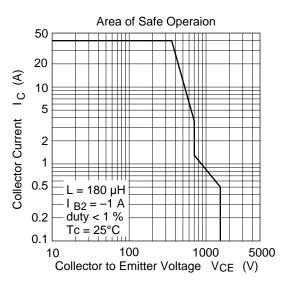
Note: 1. Value at Tc = 25°C

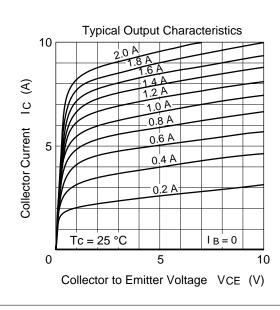
## **Electrical Characteristics** (Ta = 25°C)

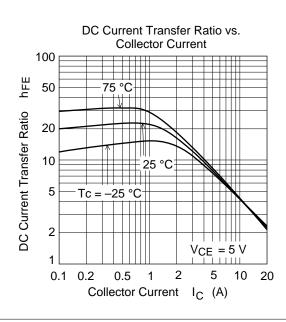
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	700			V	I <sub>C</sub> = 10mA, R <sub>BE</sub> = •
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_{E} = 10 \text{mA}, I_{C} = 0$
Collector cutoff current	I <sub>CES</sub>	_	_	500	μΑ	$V_{CE} = 1500V, R_{BE} = 0$
DC current transfer ratio	h <sub>FE1</sub>	10	_	40		$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{A}$
DC current transfer ratio	h <sub>FE2</sub>	3.5	_	6.5		$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{A}$
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	_	_	5	V	I <sub>C</sub> = 12A, I <sub>B</sub> = 4A
Base to emitter saturation voltage	V <sub>BE(sat)</sub>	_	_	1.5	V	$I_{\rm C} = 12A, I_{\rm B} = 4A$
Fall time	t <sub>f</sub>	_	0.2	0.4	μs	$I_{CP} = 8A, I_{B1} = 3A$ $f_{H} = 31.5kHz$
Fall time	t <sub>f</sub>	_	0.15	_	μs	$I_{CP} = 8A, I_{B1} = 2A$ $f_{H} = 64kHz$

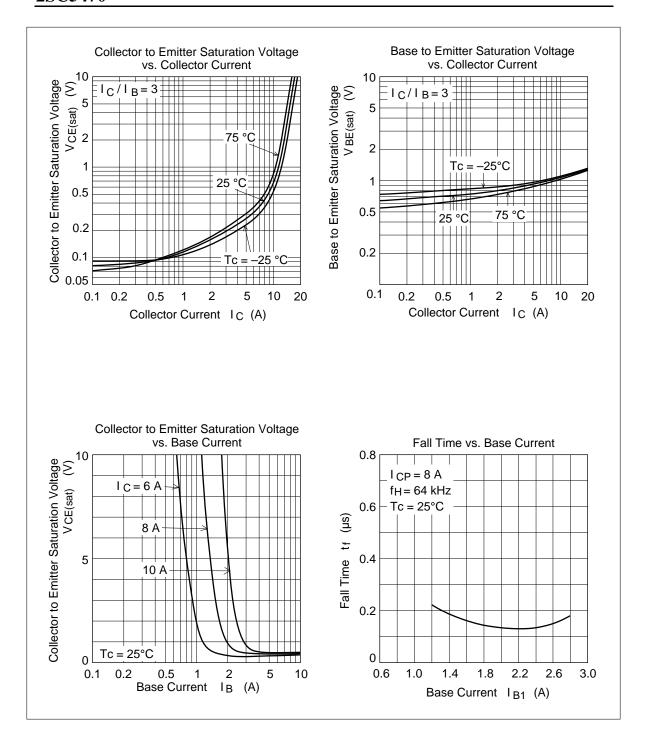
### **Main Characteristics**

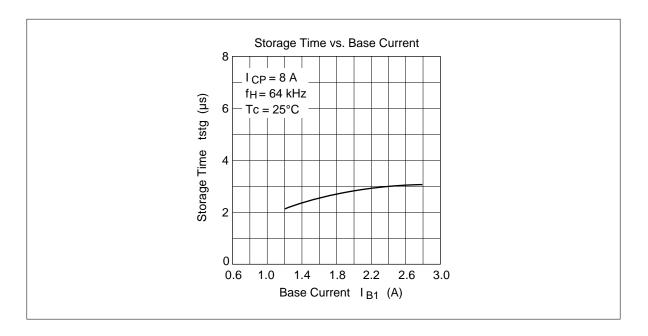




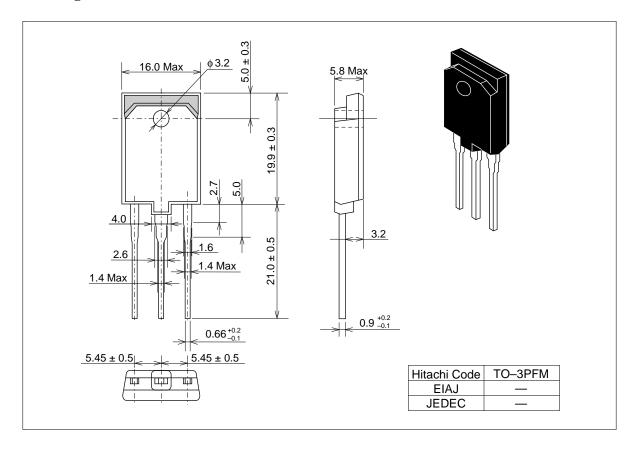








## **Package Dimensions (Unit: mm)**



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